

MSF4N60

MSF4N60 600V N-Channel MOSFET

Description

The MSF4N60 is a N-channel enhancement-mode MOSFET, providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The TIO-220AB package is universally preferred for all commercial-industrial applications

Features

- Low On Resistance
- Simple Drive Requirement
- Low Gate Charge
- Fast Switching Characteristic
- RoHS compliant package

Application (500V-600V)

- Open Framed Power Supply
- Adapter
- STB

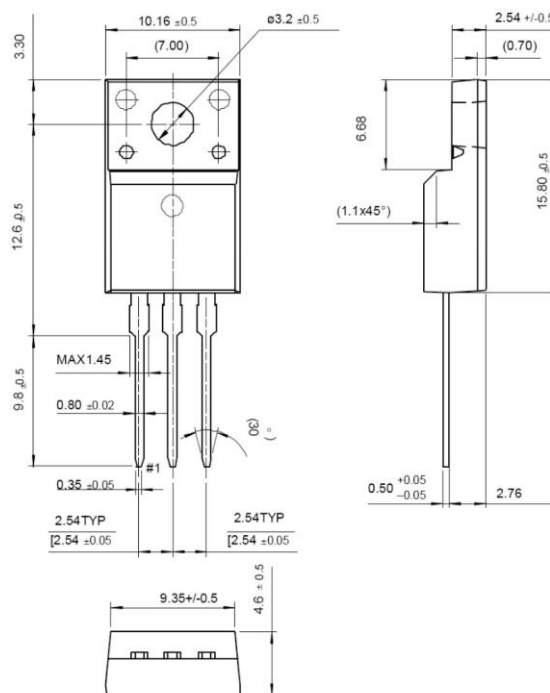
Package type : ITO220-AB

Packing & Order Information

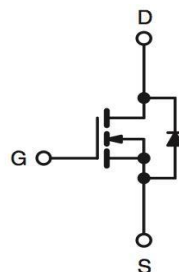
50/Tube ; 1,000/Box



**RoHS
COMPLIANT**



Graphic symbol



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

| Symbol | Parameter | Value | Unit |
|------------------|--|-------|------|
| V _{DSS} | Drain-Source Voltage | 600 | V |
| V _{GS} | Gate-Source Voltage | ±30 | V |
| I _D | Drain Current -Continuous (TC=25°C) | 4.5 | A |
| | Drain Current -Continuous (TC=100°C) | 2.6 | A |
| I _{DM} | Drain Current Pulsed | 18 | A |
| I _{AR} | Avalanche Current | 4.0 | A |
| E _{AS} | Single Pulsed Avalanche Energy | 33 | mJ |
| E _{AR} | Repetitive Avalanche Energy | 10 | mJ |
| dv/dt | Peak Diode Recovery dv/dt | 4.5 | V/ns |
| T _L | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | 300 | °C |

MSF4N60

MSF4N60 600V N-Channel MOSFET

Absolute Maximum Ratings

| | | | |
|------------------|---|-------------|------|
| TPKG | Maximum Temperature for Soldering @ Package Body for 10 seconds | 260 | °C |
| P _D | Total Power Dissipation (TC=25°C) | 31 | W |
| | Derating Factor above 25 °C | 0.25 | W/°C |
| T _{STG} | Operating and Storage Temperature Range | -55 to +150 | °C |
| T _J | Storage Temperature | 150 | °C |

Notes ;

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I_{AS}=4A, V_{DD}=50V, L=8mH, V_G=10V, Starting T_J=25°C
3. I_{SD}≤4A, di/dt≤100A/μs, V_{DD}≤BV_{DSS}, Starting T_J=25°C

Thermal Characteristics (Tc=25°C unless otherwise noted)

| Symbol | Parameter | Max. | Units |
|------------------|---|------|-------|
| R _{θJC} | Thermal Resistance, Junction-to-Case | 3.7 | °C/W |
| R _{θJA} | Thermal Resistance, Junction-to-Ambient | 62.5 | |

Static Characteristics

| Symbol | Parameter | Test Conditions | Min | Typ. | Max. | Units |
|--|---|---|-----|------|---------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} = 0 V , I _D = 250μA | 600 | -- | -- | V |
| ΔBV _{DSS} /ΔT _J | Breakdown Voltage Temperature Coefficient | I _D = 250μA, Referenced to 25°C | -- | 0.6 | -- | V/°C |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D = 250μA | 2.0 | -- | 4.0 | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 600 V , V _{GS} = 0 V V _{DS} = 480 V , T _C = 125°C | -- | -- | 1 10 | μA |
| I _{GSS} | Gate-Body Leakage Forward | V _{GS} = ±30 | -- | -- | ±100 | nA |
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} = 10 V, I _D = 2.25 A | -- | 2.0 | 2.5 | Ω |

Dynamic Characteristics

| Symbol | Parameter | Test Conditions | Min | Typ. | Max. | Units |
|---------------------|---------------------|--|-----|------|------|-------|
| t _{d(on)} | Turn-On Time | V _{DS} = 300 V, I _D = 4.5 A, R _G = 25 Ω , V _{GS} = 10 V | -- | 10 | 30 | ns |
| t _r | Turn-On Time | | -- | 40 | 80 | ns |
| t _{d(off)} | Turn-Off Delay Time | | -- | 40 | 100 | ns |
| t _f | Turn-Off Fall Time | | -- | 50 | 90 | ns |
| Q _g | Total Gate Charge | V _{DS} = 480 V, I _D = 4.5 A, V _{GS} = 10 V | -- | 16 | -- | nC |
| Q _{gs} | Gate-Source Charge | | -- | 2.5 | -- | nC |
| Q _{gd} | Gate-Drain Charge | | -- | 6.5 | -- | nC |

MSF4N60

MSF4N60 600V N-Channel MOSFET

| Dynamic Characteristics | | | | | | |
|-------------------------|------------------------------|--|-----|------|------|-------|
| Symbol | Parameter | Test Conditions | Min | Typ. | Max. | Units |
| C _{ISS} | Input Capacitance | V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0MHz | -- | 560 | -- | pF |
| C _{OSS} | Output Capacitance | | -- | 55 | -- | pF |
| C _{RSS} | Reverse Transfer Capacitance | | -- | 7 | -- | pF |

| Source-Drain Diode | | | | | | |
|--------------------|-----------|---|-----|------|------|-------|
| Symbol | Parameter | Test Conditions | Min | Typ. | Max. | Units |
| I _S | | V _D = V _G = 0 | -- | -- | 4.0 | A |
| I _{SM} | | | -- | -- | 16 | |
| V _{SD} | | I _S = 3 A, V _{GS} = 0 V | -- | -- | 1.4 | V |
| t _{rr} | | I _S = 3 A, V _{GS} = 0 V diF/dt=100A/μs | -- | 270 | -- | ns |
| Q _{rr} | | | -- | 18 | -- | μC |

Notes;

1. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

MSF4N60

MSF4N60 600V N-Channel MOSFET

■ Characteristics Curve

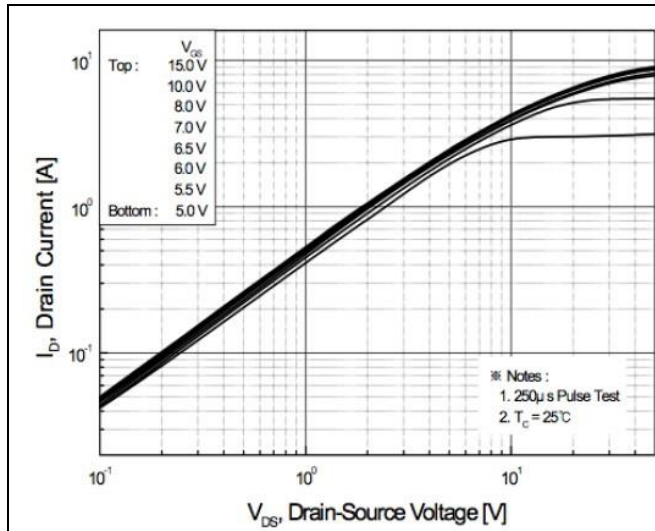


FIG.1-ON REGION CHARACTERISTICS

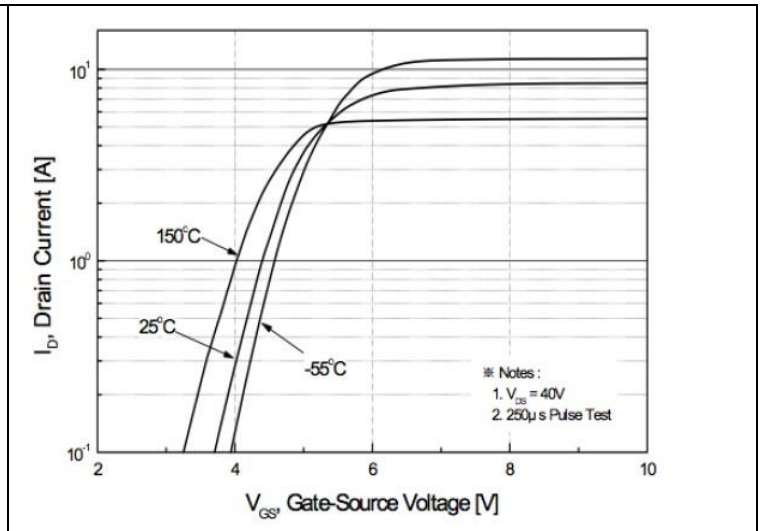


FIG.2-TRANSFER CHARACTERISTICS

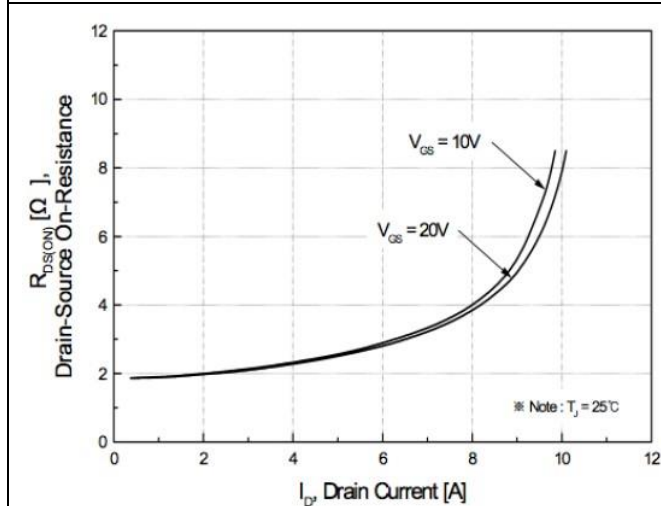


FIG.3-ON RESISTANCE VARIATION VS DRAIN CURRENT AND GATE VOLTAGE

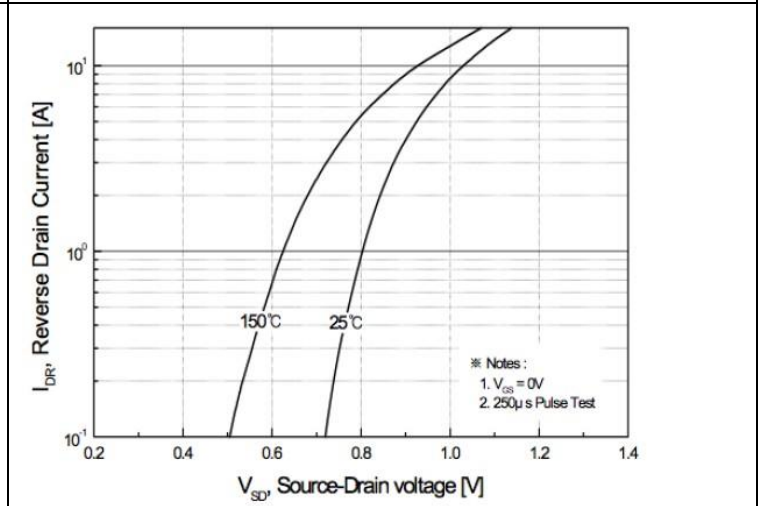


FIG.4-BODY DIODE FORWARD VOLTAGE VARIATION WITH SOURCE CURRENT AND TEMPERATURE

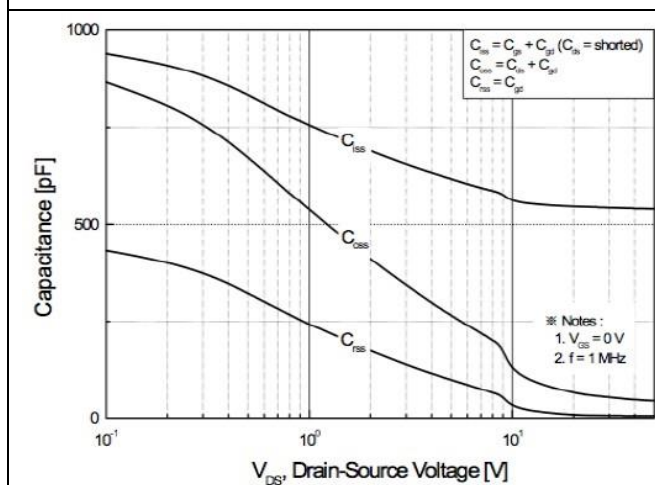


FIG.5-CAPACITANCE CHARACTERISTICS

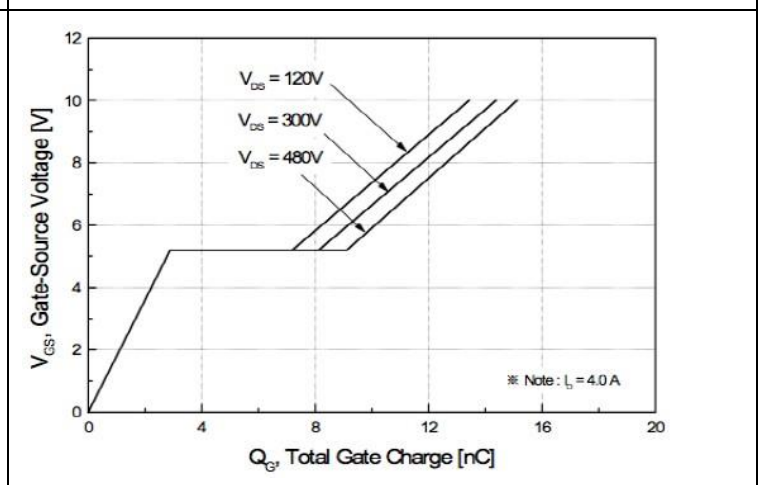


FIG.6-GATE CHARGE CHARACTERISTICS

MSF4N60

MSF4N60 600V N-Channel MOSFET

■ Characteristics Curve

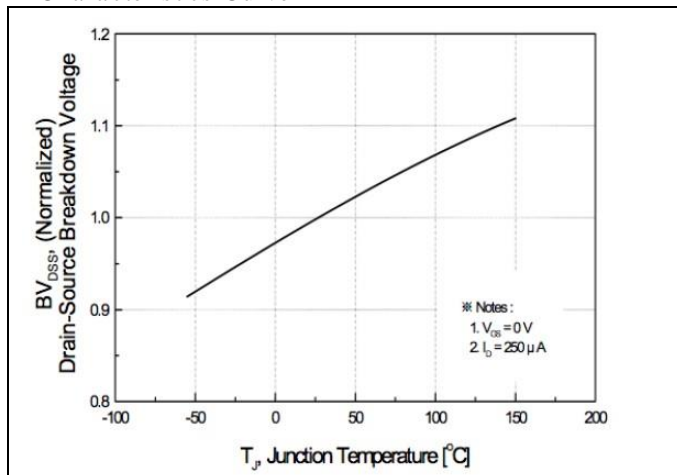


FIG.7-BREAKDOWN VOLTAGE VARIATION VS TEMPERATURE

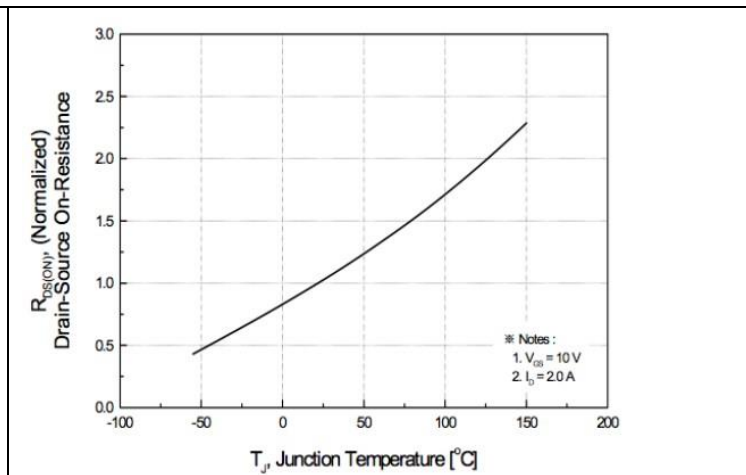


FIG.8-ON-RESISTANCE VARIATION VS TEMPERATURE

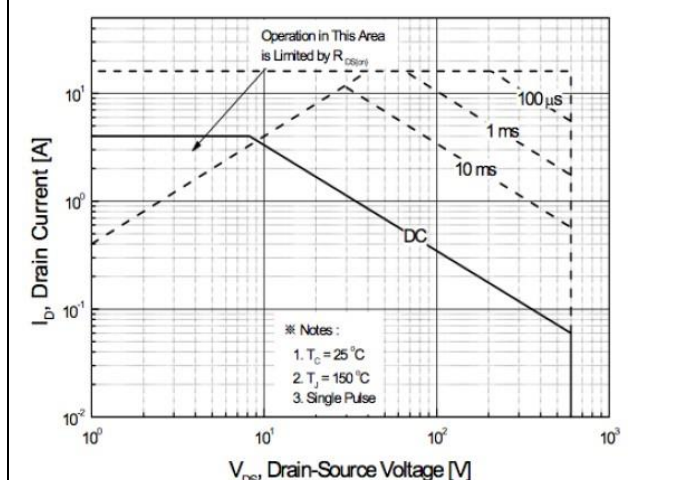


FIG.9-MAXIMUM SAFE OPERATING AREA

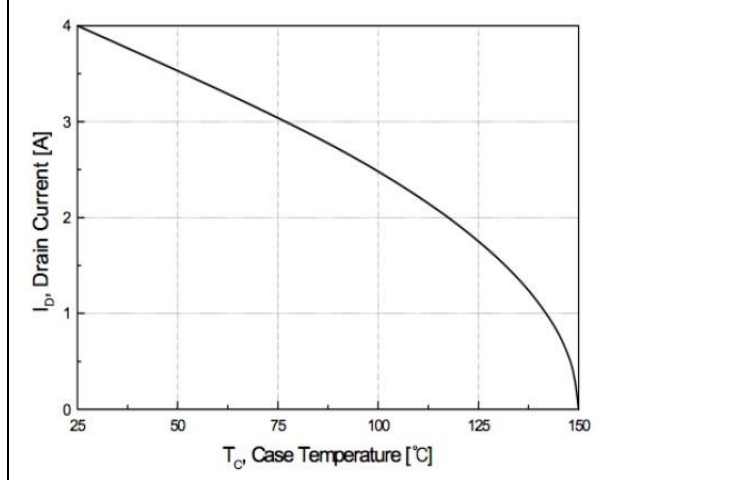


FIG.10-MAXIMUM DRAIN CURRENT VS CASE TEMPERATURE

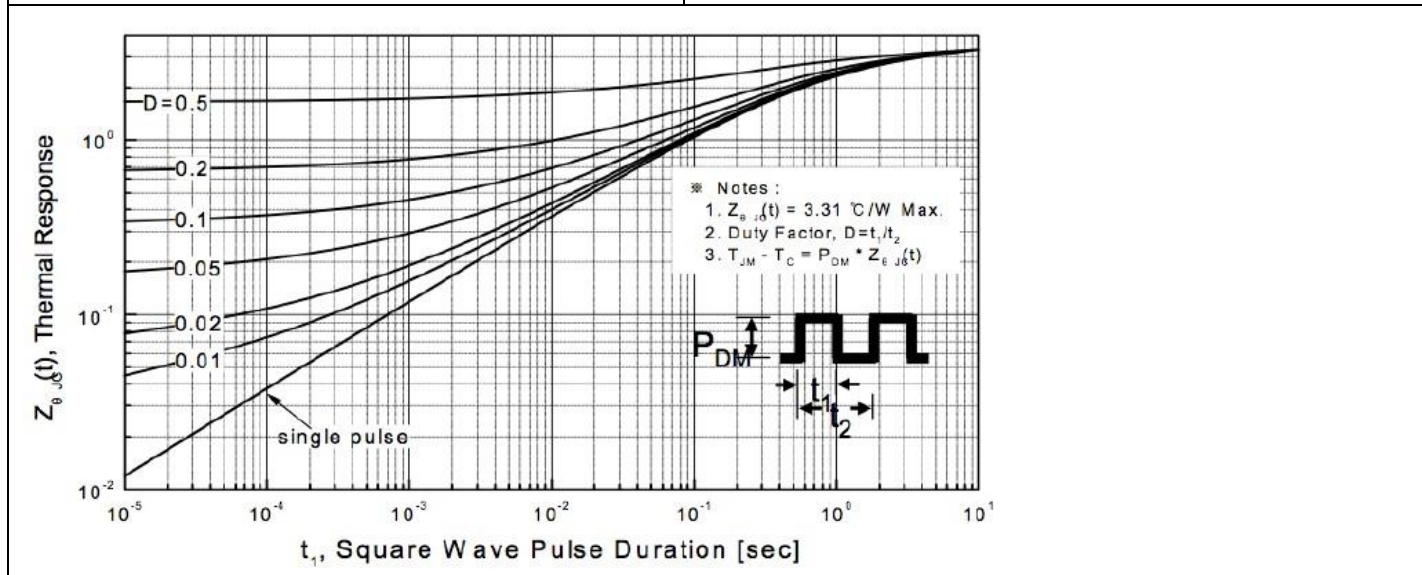


FIG.11-TRANSIENT THERMAL RESPONSE CURVE

MSF4N60

MSF4N60 600V N-Channel MOSFET

■Characteristics Test Circuit & Waveform

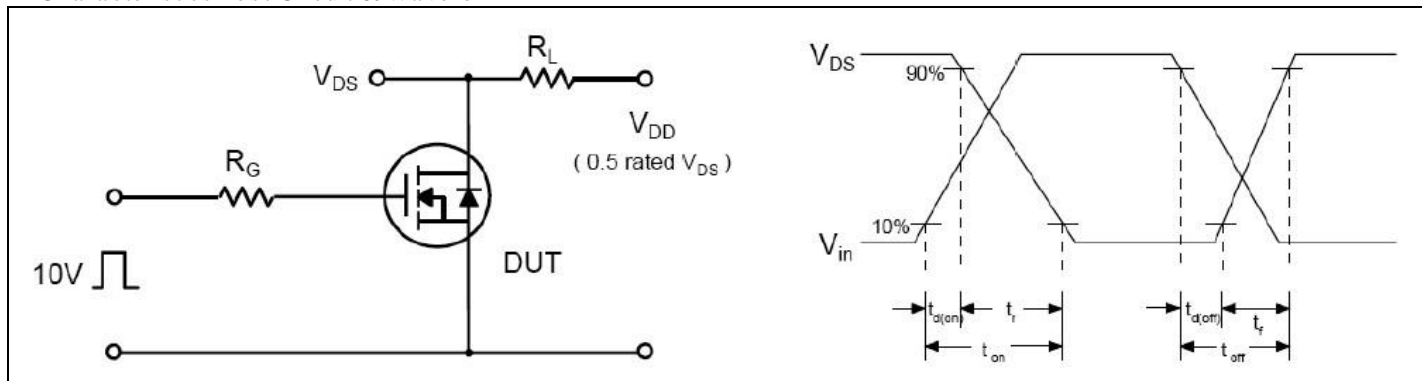


Fig 12. Resistive Switching Test Circuit & Waveforms

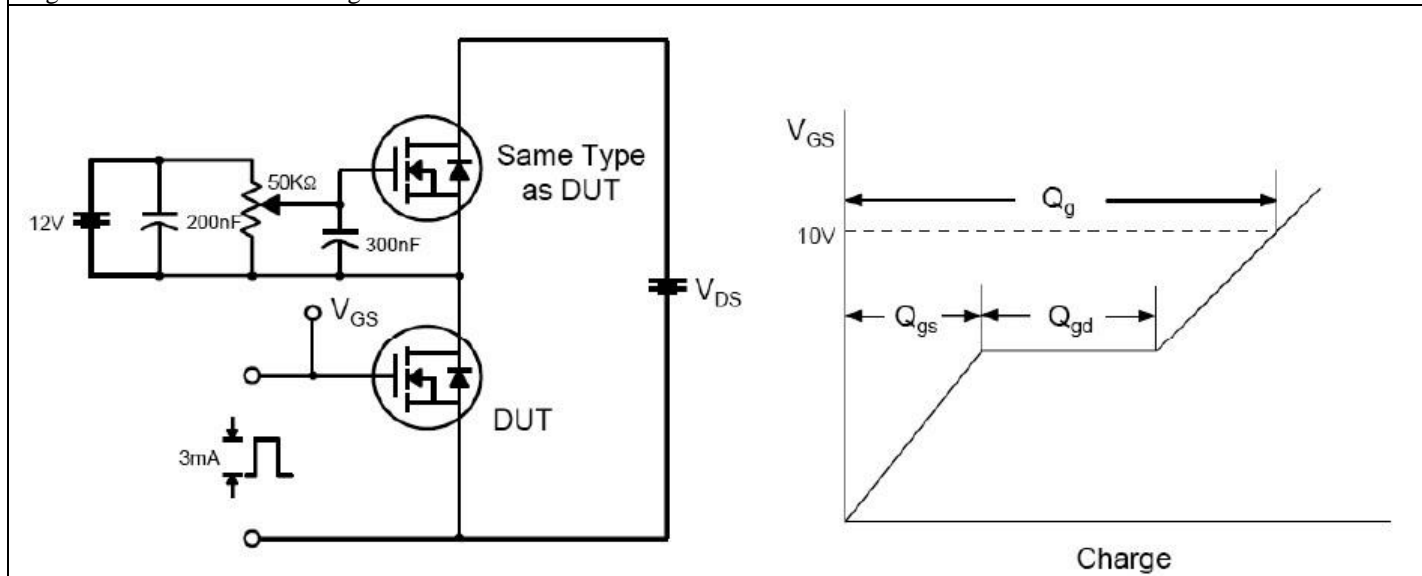


Fig 13. Gate Charge Test Circuit & Waveform

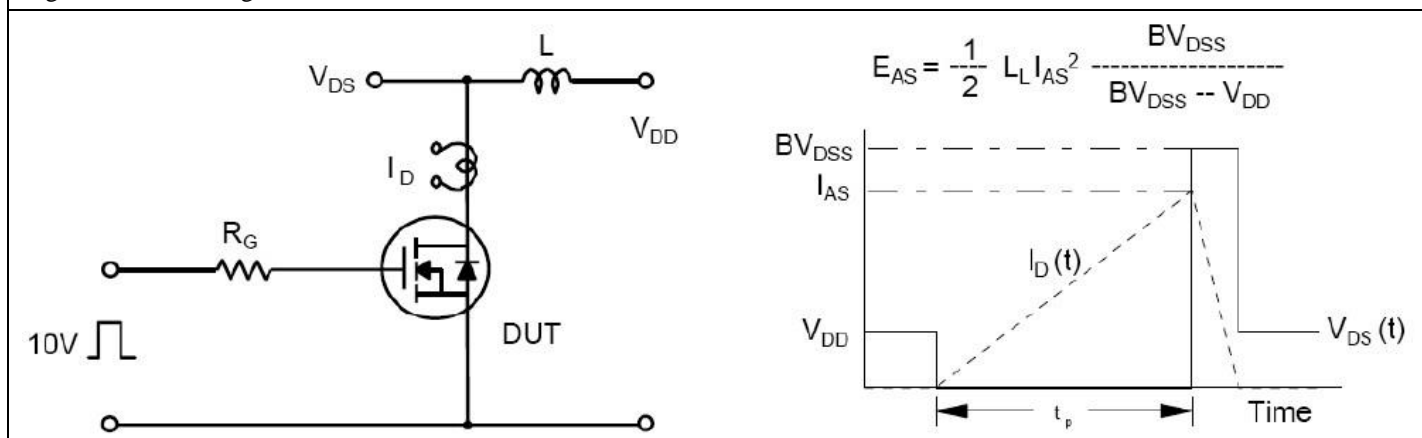


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

MSF4N60

MSF4N60 600V N-Channel MOSFET

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Bruckewell Technology Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Bruckewell"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product. Bruckewell makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Bruckewell disclaims

- (i) Any and all liability arising out of the application or use of any product.
- (ii) Any and all liability, including without limitation special, consequential or incidental damages.
- (iii) Any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Bruckewell's knowledge of typical requirements that are often placed on Bruckewell products in generic applications.

Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time.

Product specifications do not expand or otherwise modify Bruckewell's terms and conditions of purchase, including but not limited to the warranty expressed therein.